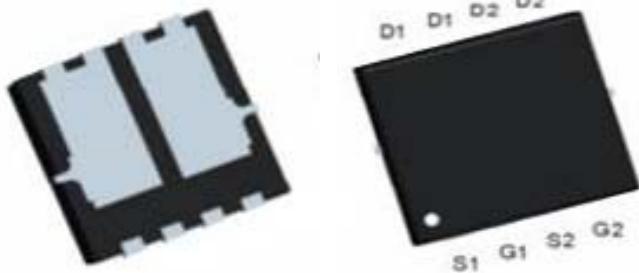


Dual N-Channel 30V(D-S) MOSFET

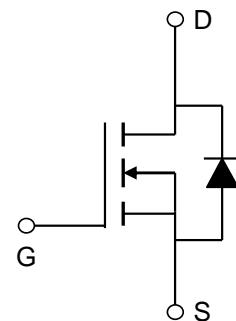
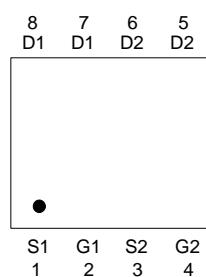
Product summary			Features
V _{DS}	30	V	<ul style="list-style-type: none"> High density cell design for low R_{ds(on)} Trench Power LV MOSFET technology RoHS and Halogen-Free compliant
R _{DS(ON)} (at V _{GS} =10V) Typ.	11	mΩ	
R _{DS(ON)} (at V _{GS} =4.5V) Typ.	14	mΩ	
I _D (T _c =25°C)	30	A	

Pin Configuration

DFN3.3x3.3-8L



Top View



Packing Information

Device	Marking	Reel Size	Tape Width	Quantity
ECQ3622	Q3622	13'	12mm	5000pcs

Absolute Maximum Ratings (at TA=25°C Unless Otherwise Noted)

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	30	V
V _{GS}	Gate-Source Voltage	±20	V
I _D	Continuous Drain Current at V _{GS} =10V	T _c =25°C	A
		T _c =100°C	A
I _{DM}	Pulse Drain Current Tested	115	A
P _D	Power Dissipation	T _c =25°C	W
T _J , T _{STG}	Junction and Storage Temperature Range	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typical	Units
R _{θJA}	Thermal Resistance-Junction to ambient	30	°C/W

Electrical Characteristics (at $T_J = 25^\circ\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
Static Parameters						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	30	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=30\text{V}, V_{\text{GS}}=0\text{V}$	--	--	1	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=\pm 20\text{V}$	--	--	± 100	nA
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.0	1.6	2.5	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=20\text{A}$	--	11	13	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=10\text{A}$	--	14	18	$\text{m}\Omega$
V_{SD}	Forward Voltage	$I_{\text{SD}}=15\text{A}, V_{\text{GS}}=0\text{V}$	--	0.9	1.2	V
Dynamic Parameters						
C_{iss}	Input Capacitance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=15\text{V}$ $f=1\text{MHz}$	--	972	--	pF
C_{oss}	Output Capacitance		--	201	--	pF
C_{rss}	Reverse Transfer Capacitance		--	131	--	pF
Q_g	Total Gate Charge	$V_{\text{DS}}=15\text{V}, I_{\text{D}}=30\text{A}$ $V_{\text{GS}}=10\text{V}$	--	27	--	nC
Q_{gs}	Gate-Source Charge		--	8	--	nC
Q_{gd}	Gate-Drain Charge		--	7	--	nC
Switching Parameters						
$t_{\text{D}(\text{on})}$	Turn-on Delay Time	$V_{\text{DD}}=20\text{V}, I_{\text{D}}=2\text{A}$ $R_{\text{G}}=3\Omega, V_{\text{GS}}=10\text{V}$	--	7	--	nS
t_r	Turn-on Rise Time		--	15	--	nS
$t_{\text{D}(\text{off})}$	Turn-off Delay Time		--	28	--	nS
t_f	Turn-off Fall Time		--	9	--	nS
t_{rr}	Reverse Recovery Time	$I_{\text{F}}=15\text{A}$ $di/dt=100\text{A}/\mu\text{s}$	--	24	--	nS
Q_{rr}	Reverse Recovery Charge		--	28	--	nC

Typical Characteristics

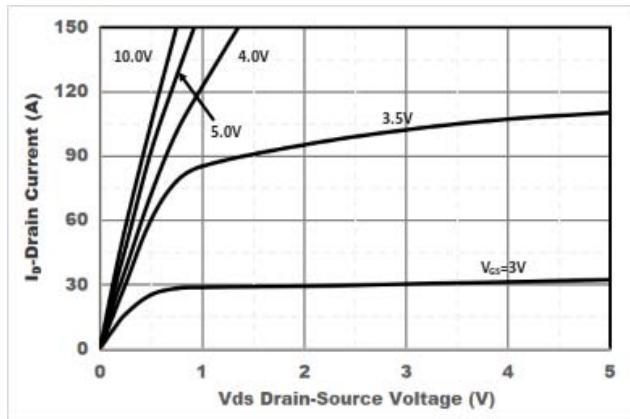


Figure1. Output Characteristics

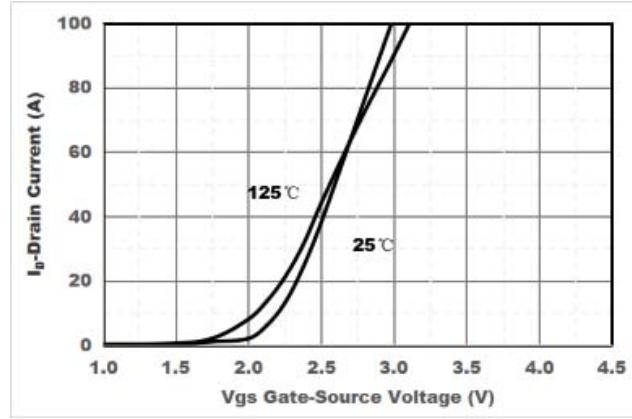


Figure2. Transfer Characteristics

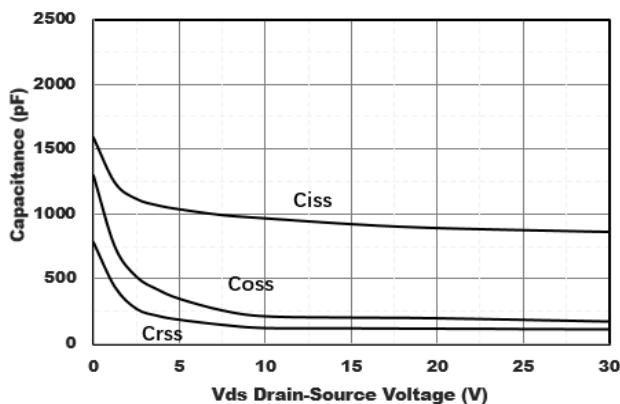


Figure3. Capacitance Characteristics

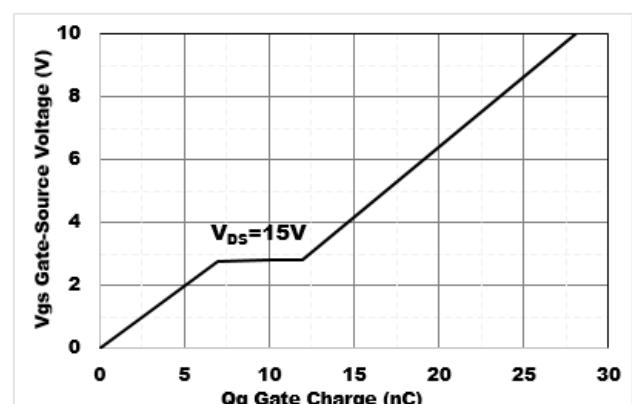


Figure4. Gate Charge

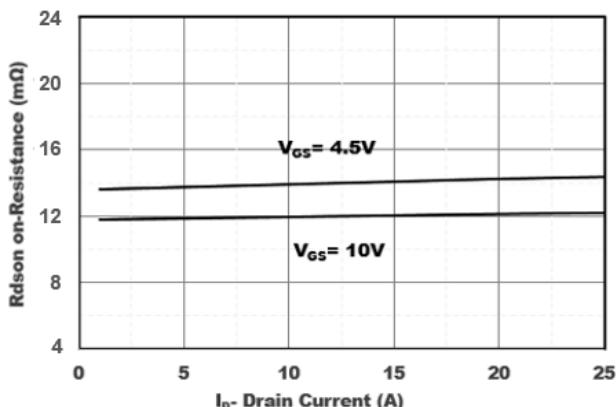


Figure5. Drain-Source on Resistance

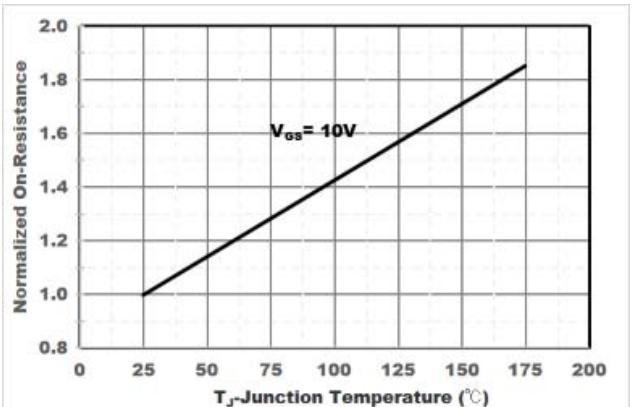


Figure6. Drain-Source on Resistance

Typical Characteristics

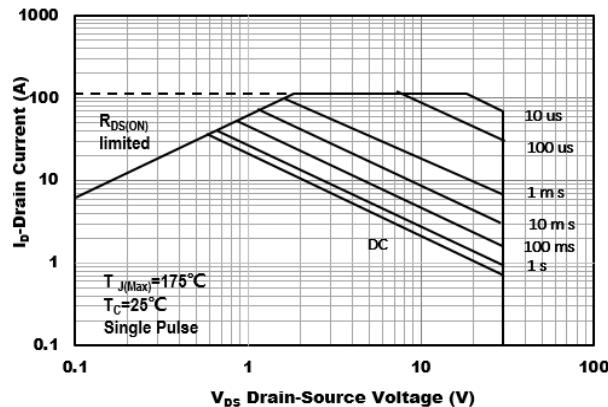


Figure7. Safe Operation Area

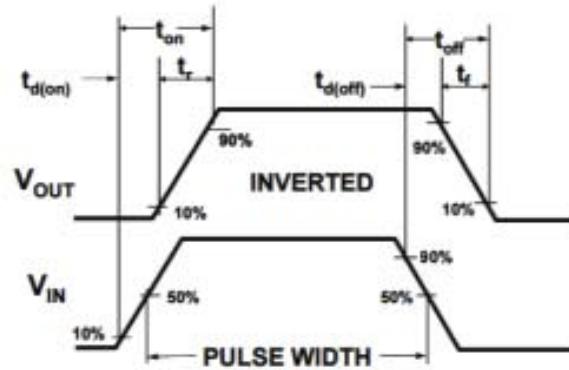
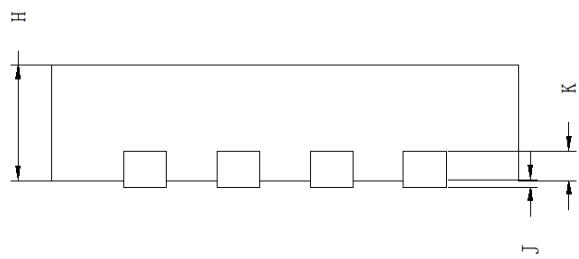
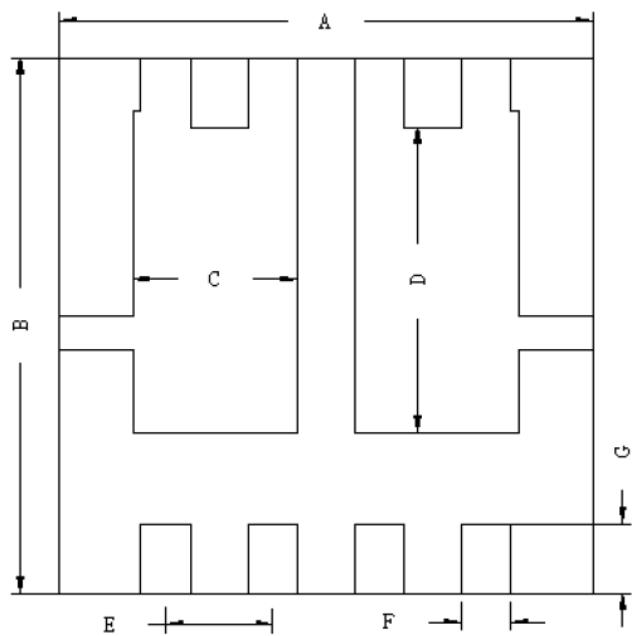


Figure8. Switching wave

DFN3.3X3.3-8L Package Information



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	3.20	3.25	3.30
B	3.20	3.25	3.30
C	0.95	1.00	1.05
D	1.80	1.85	1.90
E	0.65 BSC		
F	0.25	0.30	0.35
G	0.375	0.425	0.475
H	0.75	0.80	0.85
J			0.05
K	0.2 REF		